

AMENDMENTS TO THE CLAIMS

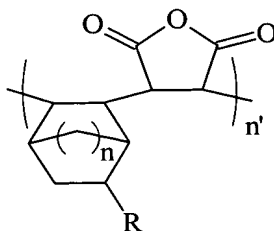
This listing of claims will replace all prior versions and listings of claims in the application.

Claims 1-18 (Previously Canceled)

19. (Currently Amended) A method of fabricating a device, comprising:

fabricating an integrated circuit chip, the integrated circuit chip including
a plurality of electrical bond pads;
fabricating a substrate;
positioning the integrated circuit chip relative to the substrate;
providing electrical connection between the integrated circuit chip and the
substrate during a reflow operation;
providing an underfill composition between the integrated circuit chip and the
substrate, the underfill composition including
a resin; and

a curing agent selected from the group consisting of low molecular weight maleic anhydride polymers, low molecular weight maleic anhydride oligomers, and a mixture thereof, wherein if the maleic anhydride polymer is a copolymer comprising norbornene, then the copolymer has the following structural formula: ~~maleic anhydride oligomers, maleic anhydride copolymers, and a mixture thereof,~~ having the formula:



where n is 1 to 3, n' is 5 to 50, and in which R is selected from the group consisting of alkyl, aryl, substituted aryls, esters, ethers, lactones, anhydrides, alcohols, nitriles, epoxy, carboxylic acids and mixtures thereof.

20. (Original) The method according to claim 19 wherein the underfill composition is provided simultaneously during reflow.

21. (Original) The method according to claim 19 wherein the underfill composition is provided after reflow.

22. (Original) The method according to claim 19 wherein the underfill composition is cured.

23. (Currently Amended) The method according to claim 22 wherein the curing occurs within a temperature range of from about 130° C to about 170° C. A ~~method according to claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.~~

24. (Currently Amended) A The method according to claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.

25. (New) The method according to claim 19 wherein the maleic anhydride polymer is a copolymer selected from the group consisting of cyclohexane/maleic anhydrides, styrene/maleic anhydrides, and mixtures thereof.